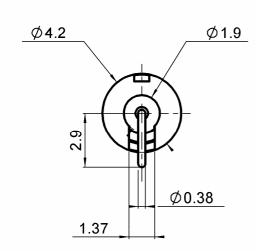
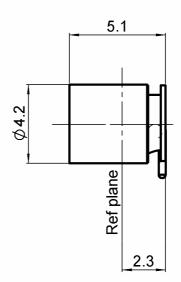
SMT TYPE - FULL DETENT - REEL 500

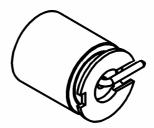
R222.508.000

Series: SMP









All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	STAINLESS STEEL + BRASS BERYLLIUM COPPER - PTFE -	PASSIVATED + GOLD 0.5 OVER NICKEL 2 GOLD 1.27 OVER NICKEL 1.27 -
-	-	-
-	-	-

Issue: 0914 C

In the effort to improve our products, we reserve the right to make changes judged to be necessary



R222.508.000

SMT TYPE - FULL DETENT - REEL 500

Series: SMP

PACKAGING

Standard Unit Other 500 - Contact us

SPECIFICATION

ENVIRONMENTAL

NA

ELECTRICAL CHARACTERISTICS

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-18} \;\; \text{GHz} \end{array}$

Operating temperature -65/+165 ° C
Hermetic seal NA Atm.cm3/s

VSWR **1.15*** + **0,0000** x F(GHz) Maxi

x F(GHz) Maxi Panel leakage

Insertion loss $0.12 \ \sqrt{F(GHz)} \ dB \ Maxi$ RF leakage $-(NA - F(GHz)) \ dB \ Maxi$

Voltage rating Voltage rating Dielectric withstanding voltage Insulation resistance S00 Veff mini 5000 M Ω mini

OTHERS CHARACTERISTICS

Assembly instruction

Others:

C

Compliant with MIL-STD-348
*At 12.4GHz - Performance strongly depends on lay out and pcb material

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

6.8 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm
Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0,3200** g

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R222.508.000

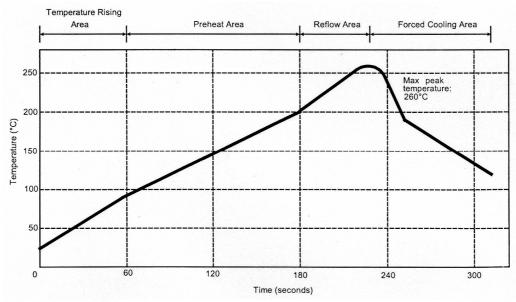
SMT TYPE - FULL DETENT - REEL 500

Series: SMP

SOLDER PROCEDURE

- 1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 µm. Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
 - Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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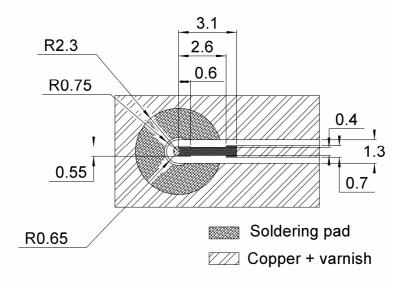
500 Series : SMP

R222.508.000

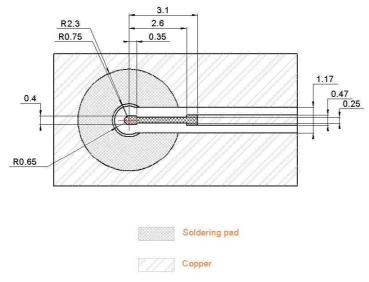
SMT TYPE - FULL DETENT - REEL 500

Substrate: RT5880 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise

RECOMMENDED PAD DIMENSIONS:



Substrate: RO4350 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise



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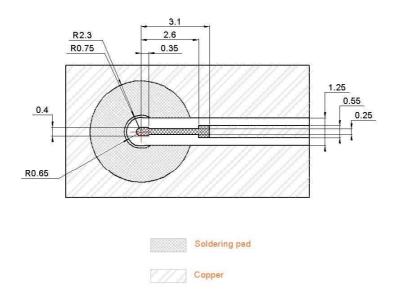


SMT TYPE - FULL DETENT - REEL 500

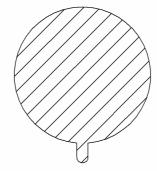
R222.508.000

Series: SMP

Substrate: RO6002 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise



SHADOW OF THE RECEPTACLE



FOR VIDEO CAMERA

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